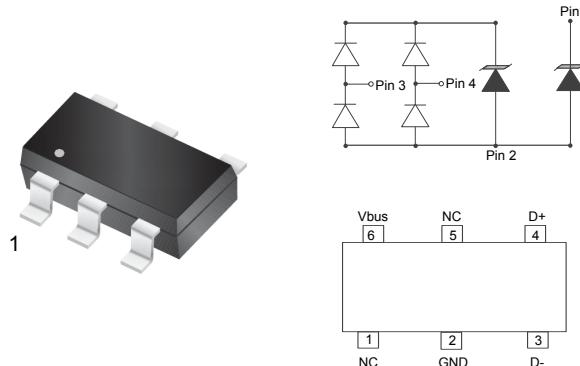


Low Capacitance ESD/TVS Array in SOT23-6

Features

- 300Watts peak pulse power ($t_p = 8/20\mu s$)
- SOT23-6 Package
- Solid-state silicon-avalanche technology
- Low clamping voltage
- Low leakage current
- Low capacitance(0.6pF typical I/O to I/O)
- ESD capability according to AEC-Q101:
human body model: class H3B: > 8 kV
- ESD Protection for high-speed data lines to:
IEC 61000-4-2 ±30KV contact ±30KV air
IEC 61000-4-4 (EFT) 40A (5/50ns)
IEC 61000-4-5 (Lightning) 20 A (8/20μs)



Mechanical Data

- **Case:** SOT23-6 (plastic package).
Lead free; RoHS compliant; Halogen free
- **Molding Compound Flammability Rating:**
UL 94 V-0
- **Terminals:** High temperature soldering guaranteed:
260 °C/10 sec. at terminals

Applications

- USB 2.0, MHL
- Ethernet
- Unified Display Interface (UDI)
- Digital Visual Interface (DVI)

Absolute Maximum Ratings

Ratings at 25 °C, ambient temperature unless otherwise specified

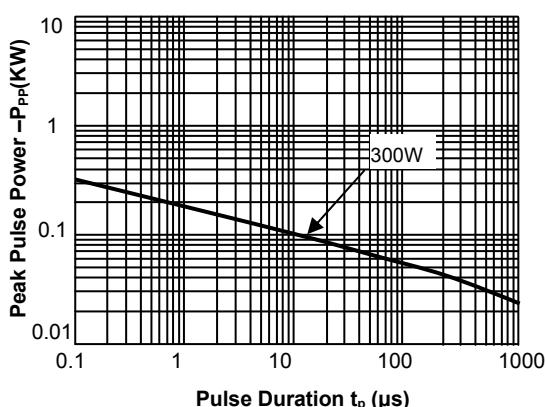
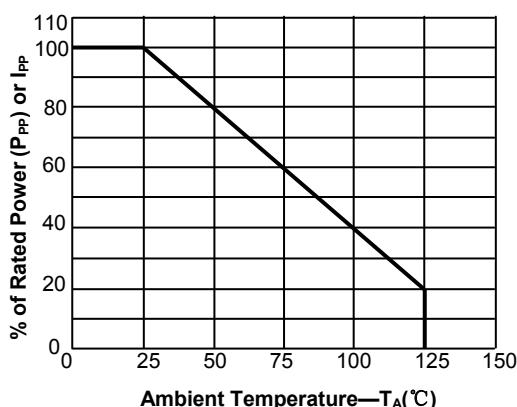
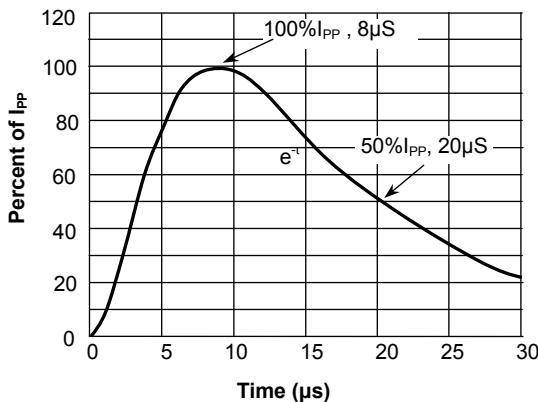
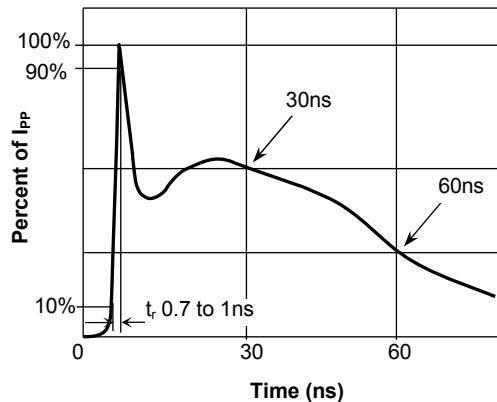
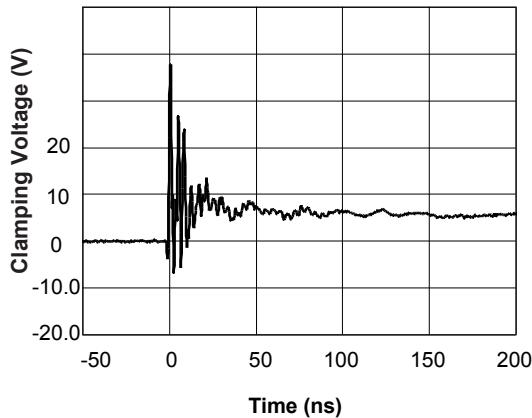
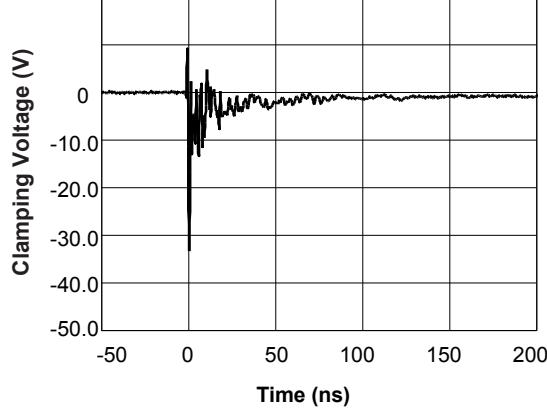
Parameter	Symbol	Value	Unit
Peak Pulse Power ($T_p=8/20\mu s$)	P _{PP}	300	W
ESD contact/air discharge (IEC-61000-4-2)	V _{ESD}	30/30	kV
Peak Pulse Current ($t_p = 8/20\mu s$)	I _{PP}	20	A
Junction Temperature	T _J	-55 to +150	°C
Storage temperature	T _{STG}	-55 to +150	°C

Electrical Characteristics

($T_A = 25$ °C unless otherwise specified)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
D+,D- TVS						
Reverse Stand-Off Voltage	V _{RWM}				5.0	V
Reverse Breakdown Voltage	V _{BR}	I _T =1mA	6.0	8.0		V
Reverse Leakage Current	I _R	V _{RWM} =5V,T=25°C		0.2	0.5	uA
Clamping Voltage	V _C	I _{PP} =8.0A,T _p =8/20μs		12	18	V
Junction Capacitance	C _j	V _R = 0V, f = 1MHz I/O to I/O		0.6	0.7	pF
		V _R = 0V, f = 1MHz I/O to GND		1.2	1.4	pF
Vbus TVS						
Reverse Stand-Off Voltage	V _{RWM}				5.0	V
Reverse Breakdown Voltage	V _{BR}	I _T =1mA	6.0			V
Reverse Leakage Current	I _R	V _{RWM} =5V,T=25°C			1	uA
Clamping Voltage	V _C	I _{PP} =20A,T _p =8/20μs		12	15	V
Junction Capacitance	C _j	V _R = 0V, f = 1MHz VCC to GND		160		pF

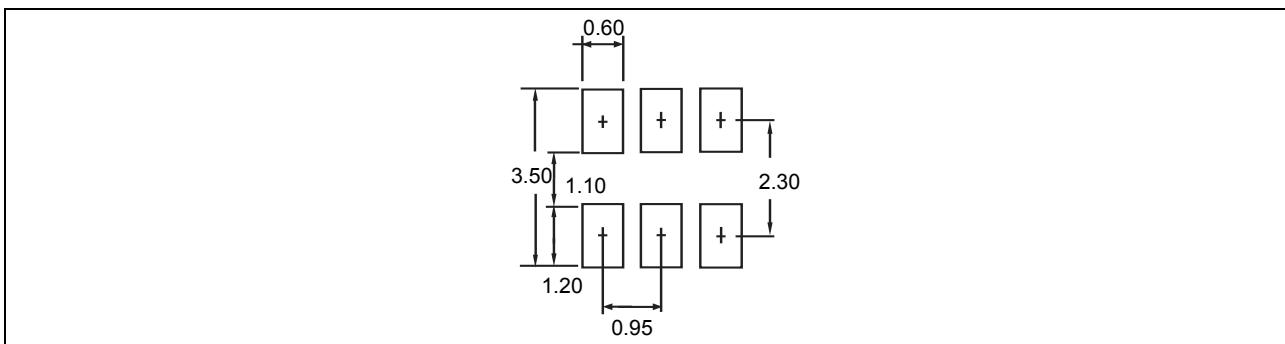
Typical Characteristics ($T_{amb} = 25^{\circ}\text{C}$ unless otherwise specified)

Fig.1 Peak Pulse Power Rating Curve

Fig.2 Pulse Derating Curve

Fig.3 Pulse Waveform-8/20μs

Fig.4 Pulse Waveform-ESD(IEC61000-4-2)

Fig.5 ESD Clamping of I/O to GND (+8kV Contact per IEC 61000-4-2)

Fig.6 Fig.5 ESD Clamping of I/O to GND (-8kV Contact per IEC 61000-4-2)


Package Dimensions

Symbol	Dimensions in millimeters	
	Min	Max
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.300	0.500
c	0.100	0.200
D	2.820	3.020
E1	1.500	1.700
E	2.650	2.950
e	0.950(BSC)	
e1	1.800	2.000
L	0.300	0.600
θ	0°	8°

Pad dimensions



Package information

Pkg type	a	B	C	d	E	F	P0	P	P1	W
Dimensions are in millimeter										
SOT-23-6	3.17	3.23	1.37	Ø1.55	1.75	3.50	4.00	4.00	2.00	8.00

Ordering information

Order code	Marking	Package	Packaging option	Base quantity	Packaging specification
TEST236LC5VUTL	5Q	SOT23-6	Tape and reel	3000pcs / reel	EIA STD RS-481